

**Amendments to the Specification**

Please replace the title with the following new title.

~~Semiconductor Processing Methods of Forming Photoresist over Silicon Nitride~~  
~~Materials, and Semiconductor Wafer Assemblies Comprising Photoresist over Silicon~~  
~~Nitride Materials~~

At page 1, please replace the Related Patent Data section with the following new Related Patent Data Section.

**RELATED PATENT DATA**

This application resulted from a continuation application from U.S. Patent Application Serial No. 09/995,372, filed on November 26, 2001 which resulted from a continuation application of U.S. Patent Application Serial No. 09/724,749, which was filed on November 27, 2000, now U.S. Patent No. 6,417,559 which is a divisional application of U.S. Patent Application Serial No. 09/457,093, which was filed December 7, 1999, now U.S. Patent No. 6,323,139 This application which is a continuation-in-part of U.S. Patent Application Serial No. 09/057,155, filed April 7, 1998, now U.S. Patent No. 6,300,253; and a continuation-in-part of U.S. Patent Application Serial No. 09/295,642, filed April 20, 1999 now U.S. Patent No. 6,297,171; which is a continuation of U.S. Patent Application Serial No. 08/567,090, now U.S. Patent No. 5,926,739.